

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shiu-Ko Jang Jian</td> <td>05/15/2013</td> </tr> <tr> <td>Chih-Nan Wu</td> <td>05/15/2013</td> </tr> <tr> <td>Chun Che Lin</td> <td>05/15/2013</td> </tr> <tr> <td>Yu-Ku Lin</td> <td>05/15/2013</td> </tr> </tbody> </table>		Name	Execution Date	Shiu-Ko Jang Jian	05/15/2013	Chih-Nan Wu	05/15/2013	Chun Che Lin	05/15/2013	Yu-Ku Lin	05/15/2013
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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CORRESPONDENCE DATA											
<p>Fax Number: 2142000853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000 Email: ipdocketing@haynesboone.com</p> <p>Correspondent Name: HAYNES AND BOONE, LLP IP Section Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219</p>											
ATTORNEY DOCKET NUMBER:	24061.2473										
NAME OF SUBMITTER:	Linda Ingram										
Signature:	/Linda Ingram/										

PATENT

Date:

06/06/2013

Total Attachments: 2

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-------------------|----|--|
| (1) | Shiu-Ko Jang Jian | of | 18F-5, No. 11, Lane 370,
Gongyuan S. Road, North District
Tainan City 704, Taiwan, R.O.C. |
| (2) | Chih-Nan Wu | of | Room 8, 11F, No. 453, Chenggong Road
West Central District
Tainan City 700, Taiwan, R.O.C. |
| (3) | Chun Che Lin | of | 6F-2, No. 7, 3th Lane, 226 Alley
Nan-Kung Street, Yong-Kong District
Tainan City, Taiwan, R.O.C. |
| (4) | Yu-Ku Lin | of | No. 91, Sisian 2 nd Street
Tainan City, Taiwan, R.O.C. |

have invented certain improvements in

HIGHT-K DIELECTRIC GRID STRUCTURE FOR SEMICONDUCTOR DEVICE

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on June 6, 2013, and assigned application number 13/911,277; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

Docket No.: 2013.0235/24061.2473
Customer No.: 000042717

applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Shiu-KoJangJian

Residence Address: 18F-5, No. 11, Lane 370, Gongyuan S. Road, North District
Tainan City 704, Taiwan, R.O.C.

Dated: May 15, 2013

Shiu-Ko Jang Jian
Inventor Signature

Inventor Name: Chih-Nan Wu

Residence Address: Room 8, 11F, No. 453, Chenggong Road, West Central District
Tainan City 700, Taiwan, R.O.C.

Dated: May 15, 2013

Chih-Nan Wu
Inventor Signature

Inventor Name: Chun Che Lin

Residence Address: 6F-2, No. 7, 3th Lane, 226 Alley, Nan-Kung Street, Yong-Kong District
Tainan City, Taiwan, R.O.C.

Dated: May 15th, 2013

May 15th, 2013
Inventor Signature

Inventor Name: Yu-Ku Lin

Residence Address: No. 91, Sisian 2nd Street, Tainan City, Taiwan, R.O.C.

Dated: May 15th, 2013

Yu-Ku Lin
Inventor Signature